



Terahertz Microprobe-enabled Near-Field Imaging for non- destructive testing applications



Protemics GmbH
Otto-Blumenthal-Str. 25
D-52074 Aachen
Germany

www.protemics.com
info@protemics.com
Phone: +49 241 8867 140
Fax: +49 241 8867 560





Outline

- **Introduction**

- Terahertz near-field microprobe technology
- Working principle and main applications

- **Application examples**

- R&D:

- THz source characterization
 - THz Metamaterial characterization

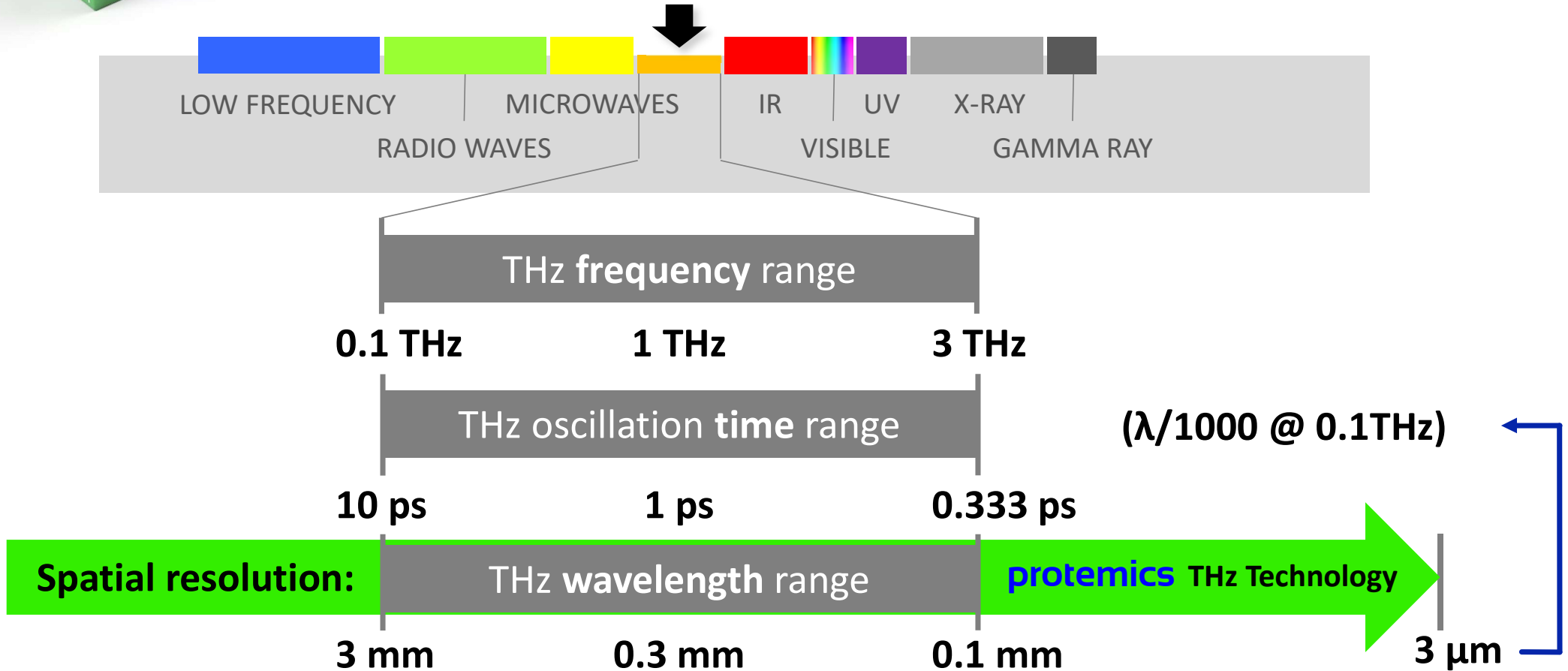
- Non-destructive testing:

- Thin-film inspection
 - Solar cells, Graphene
 - Laser weld and chip package inspection



Terahertz in numbers

TERAHERTZ

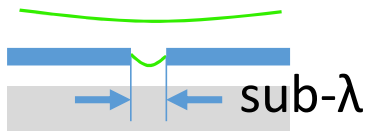




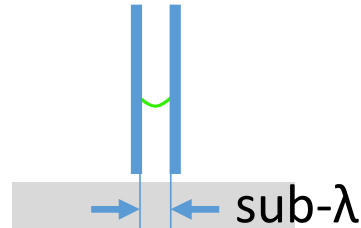
Terahertz near-field measurement methods

Passive (metal) structures to isolate/generate the near-field information:

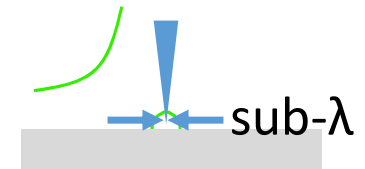
Apertures



Waveguides

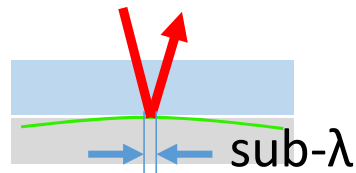


Scattering elements

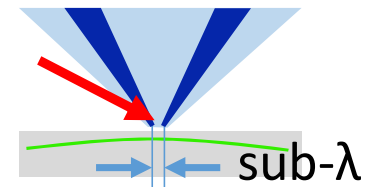


Direct detection in the near-field using **active probes**:

Electrooptic crystals



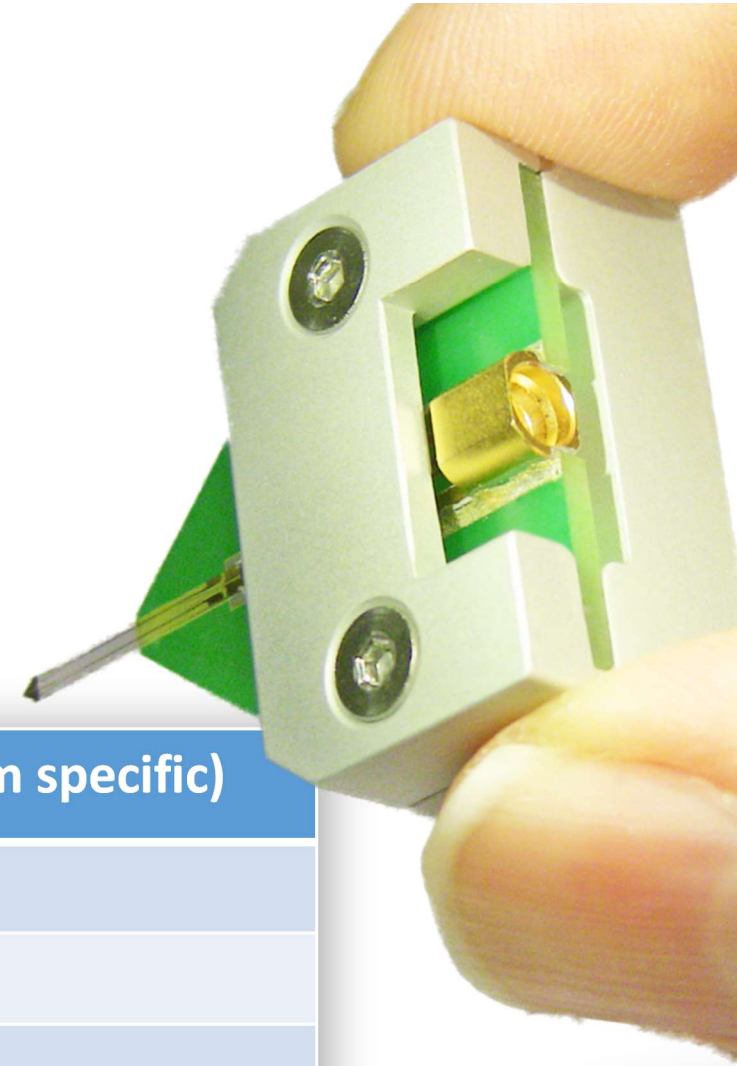
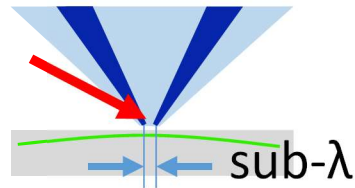
Photoconductive microprobes





Terahertz near-field microprobe

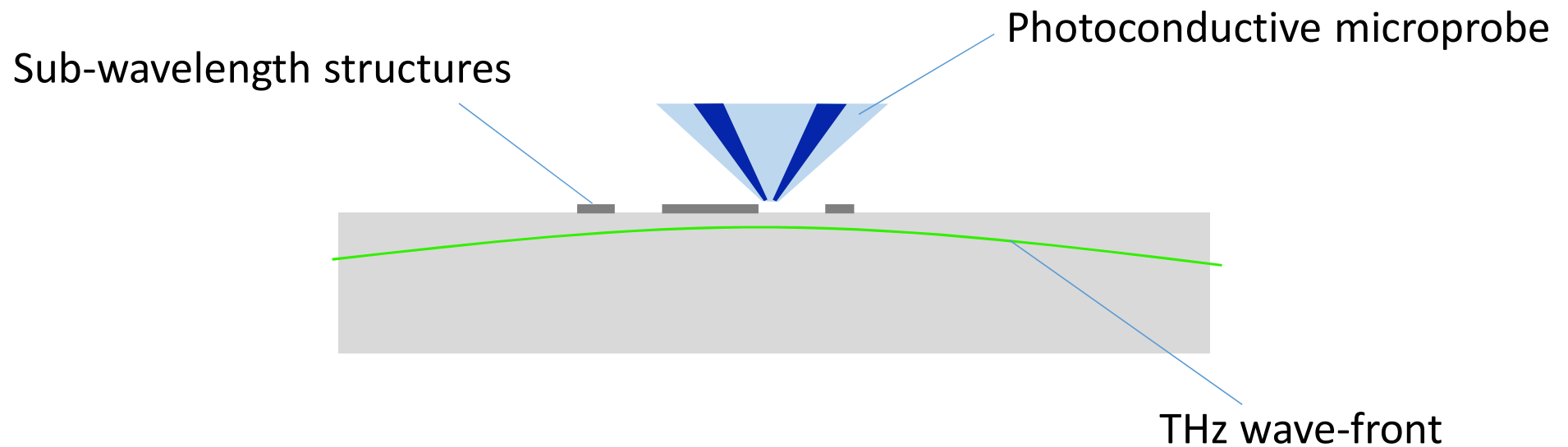
Photoconductive microprobes



Main benefits	Up to ... (system specific)
High speed	1 ms/point
High bandwidth	0.05 .. 4 THz
High spatial resolution	3 μm
Contact less/Low invasive	1 .. 1000 μm (Typ. Distance)
Large scanning area access	Quasi „unlimited“ (typ. wafer scale)



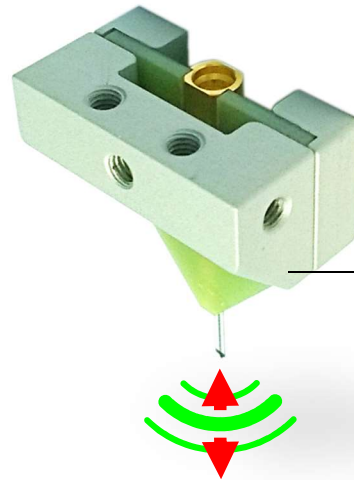
Terahertz near-field transmission imaging



Small structures can be resolved because of increased field sensitivity near the probe tip.



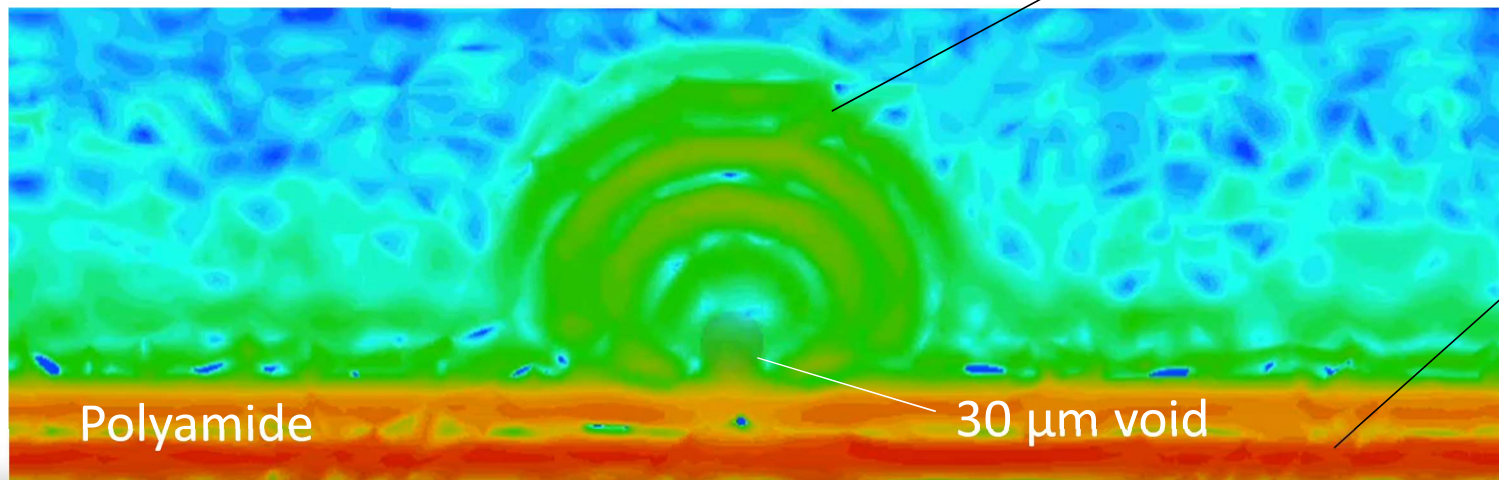
Terahertz near-field reflection imaging



THz microprobe transceiver



Scattered THz wave



Incident THz wave-front

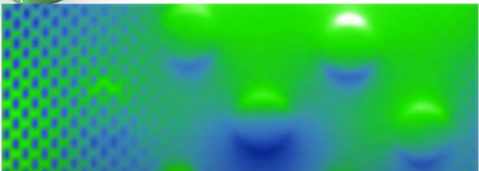
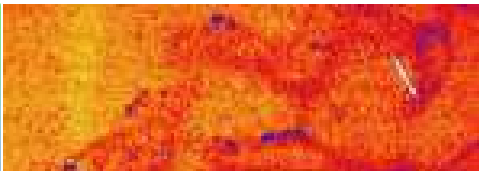

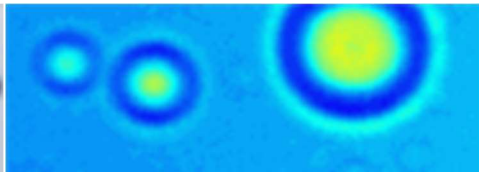
30 μm void

Small (buried) structures can be **recognized** by the scattering signal they generate. Measuring in close distance to the scatterer helps to detect these weak signals



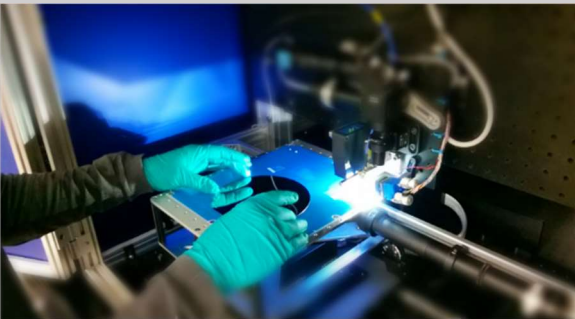
Terahertz microprobing applications:

Taking advantage of Terahertz benefits without being compromised by wavelength-based resolution limitations.

			
Terahertz Research	Wafer Inspection	Chip-Testing	Volume Screening
Application areas: <ul style="list-style-type: none"> • Metamaterials • Plasmonics • Devices • Waveguides • Sensor surfaces • Graphene 	Application areas: <ul style="list-style-type: none"> • Solar cells • Displays • Flexible electronics • Doping layers • Graphene • Transparent conductors 	Application areas: <ul style="list-style-type: none"> • Time-domain reflectometry • Fault isolation • Packaging level inspection • 3D integration • Through silicon via (TSV) 	Application areas: <ul style="list-style-type: none"> • Plastic weld inspection • Fiber inforced polymers • Chip underfill inspection • Organic layer screening
Benefits: <ul style="list-style-type: none"> • Near-field access • High-sensitivity • Low-invasiveness • Polarisation sensitive • Broadband 	Benefits: <ul style="list-style-type: none"> • Sheet resistance imaging • Contactless • Micron-scale resolution • Large-area scanning • High-speed scanning 	Benefits: <ul style="list-style-type: none"> • Market leading TDR resolution • Contactless • Non-destructive • Cost advantage 	Benefits: <ul style="list-style-type: none"> • Non-destructive • Fast inspection • Screening of opaque plastics • Detection of microdefects



Full system solution TeraCube Scientific



- Table-top THz time-domain near-field imaging system
- Transmission- or reflection-mode
- XYZ-T-scanning system
- Up to 310 mm x 310 mm scanning area



Modular configuration

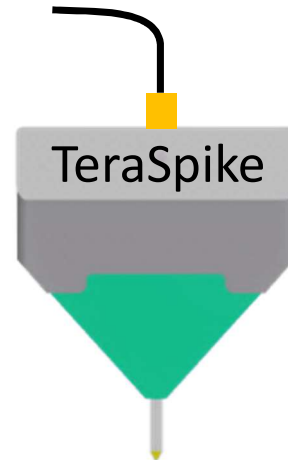
With fiber-coupled THz TDS system: TeraFlash





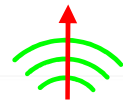
THz source characterization

Measured with TeraFlash system & TeraSpike probe

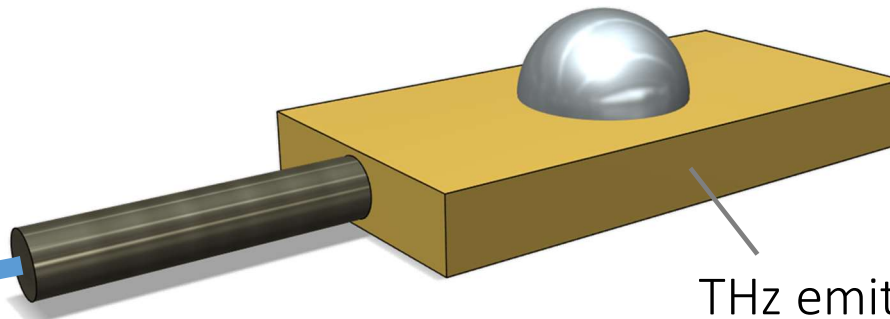


TeraSpike

THz
microprobe
detector



Pulsed THz radiation

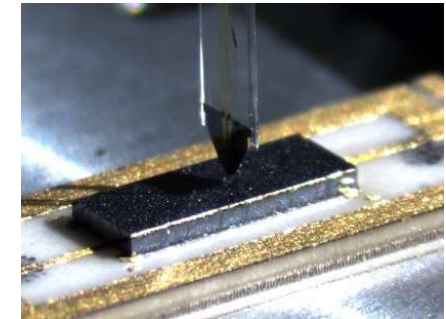
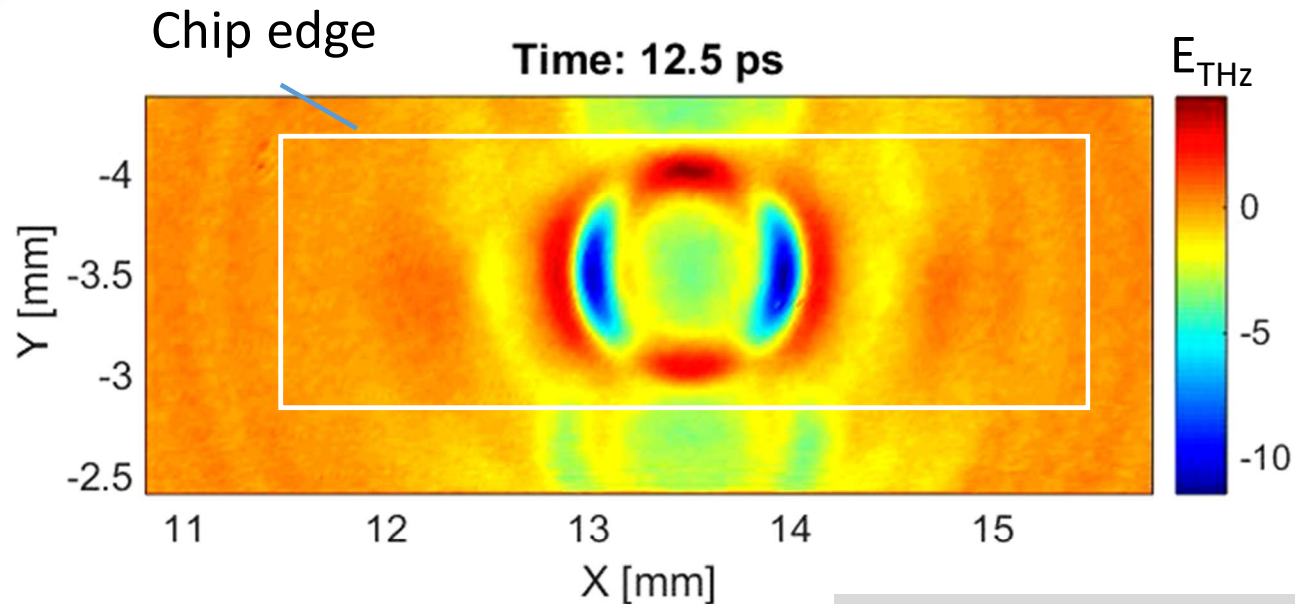


THz emitter chip (HHI)
-> xyz-scanned



THz source characterization

Measured with TeraFlash system & TeraSpike probe



*Measurement of 2,400,000 data points
at **1333 data points per second.***

Toptica TeraFlash system and emitter chip provided by:

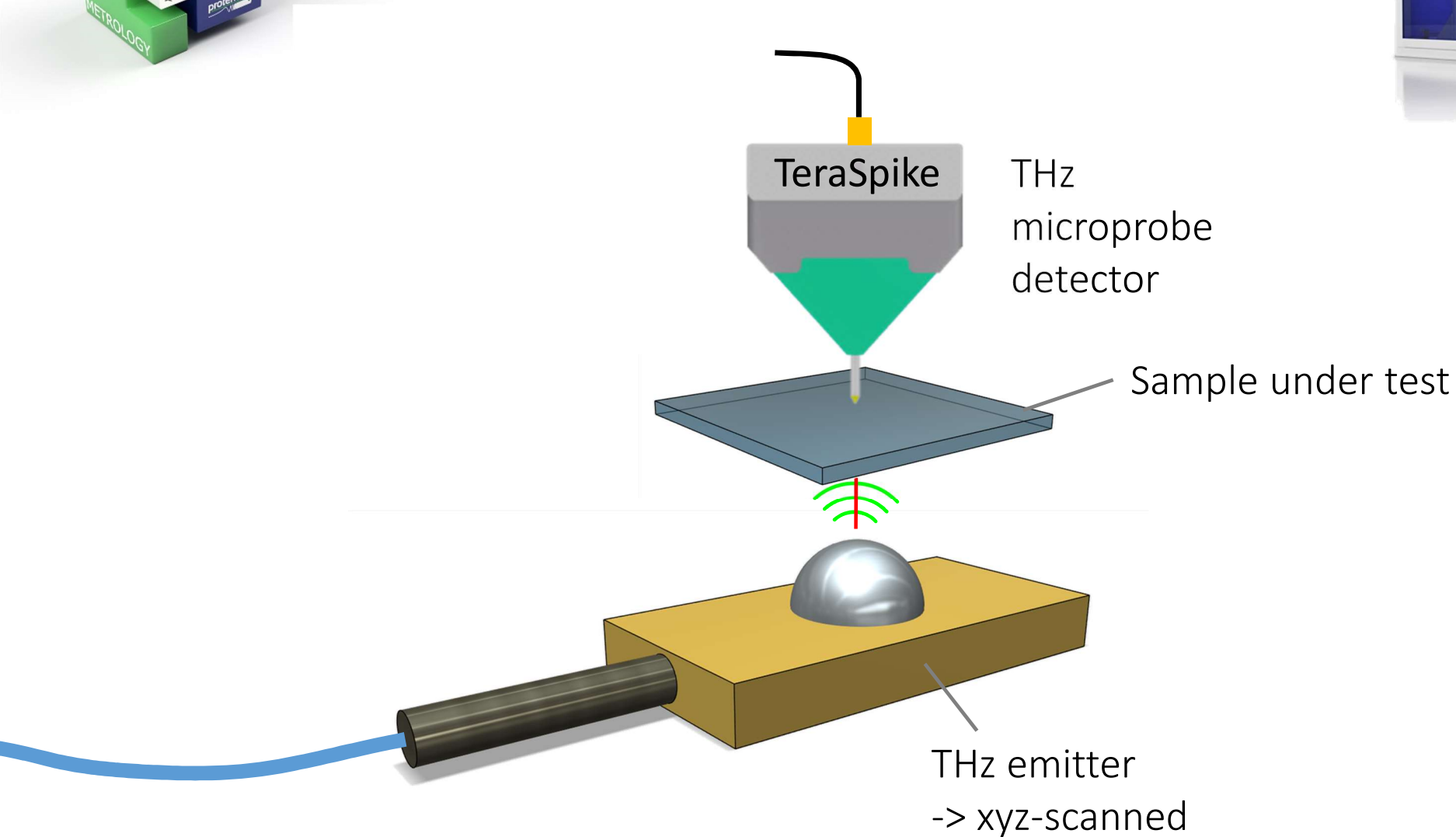


Fraunhofer-Institut für Nachrichtentechnik,
Heinrich-Hertz-Institut, HHI



THz structure characterization

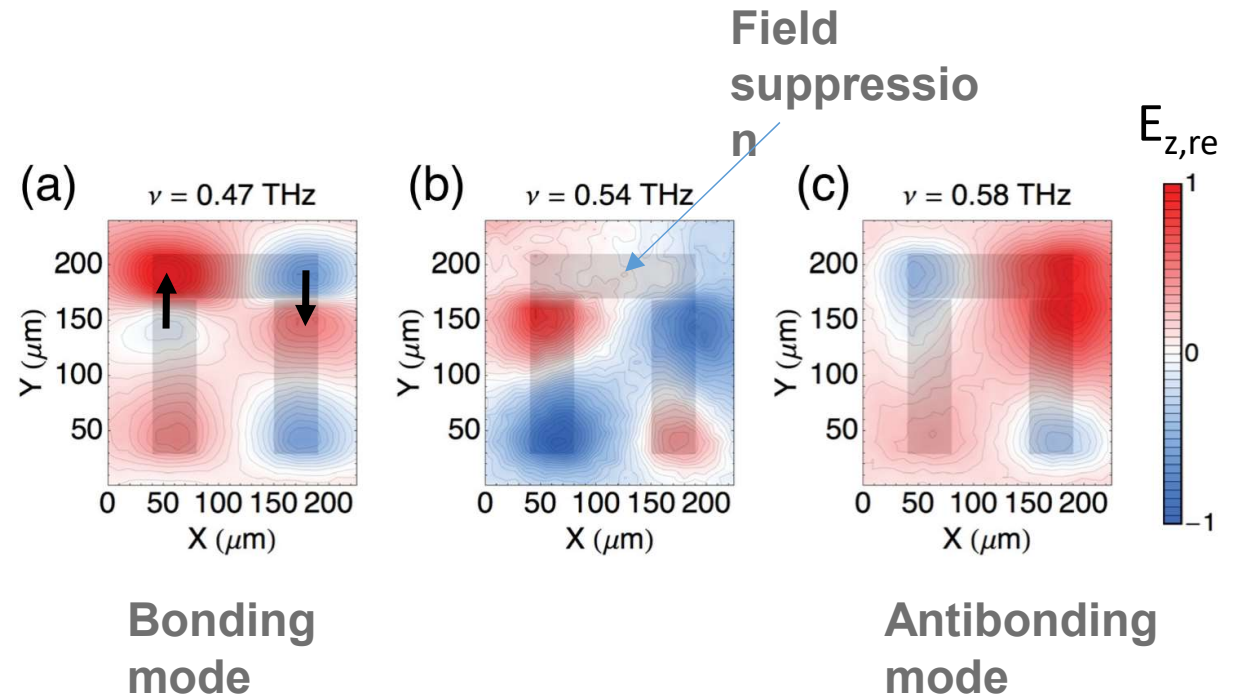
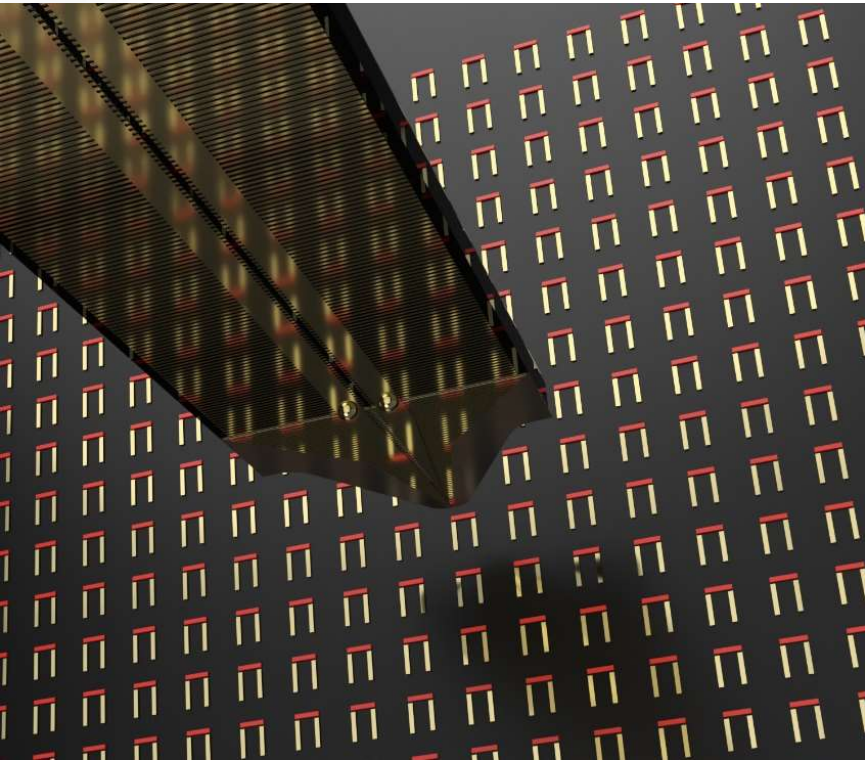
Measured with TeraSpike microprobe





Metamaterial characterization

Measured with TeraSpike microprobe



Visualizing near-field coupling in terahertz dolmens

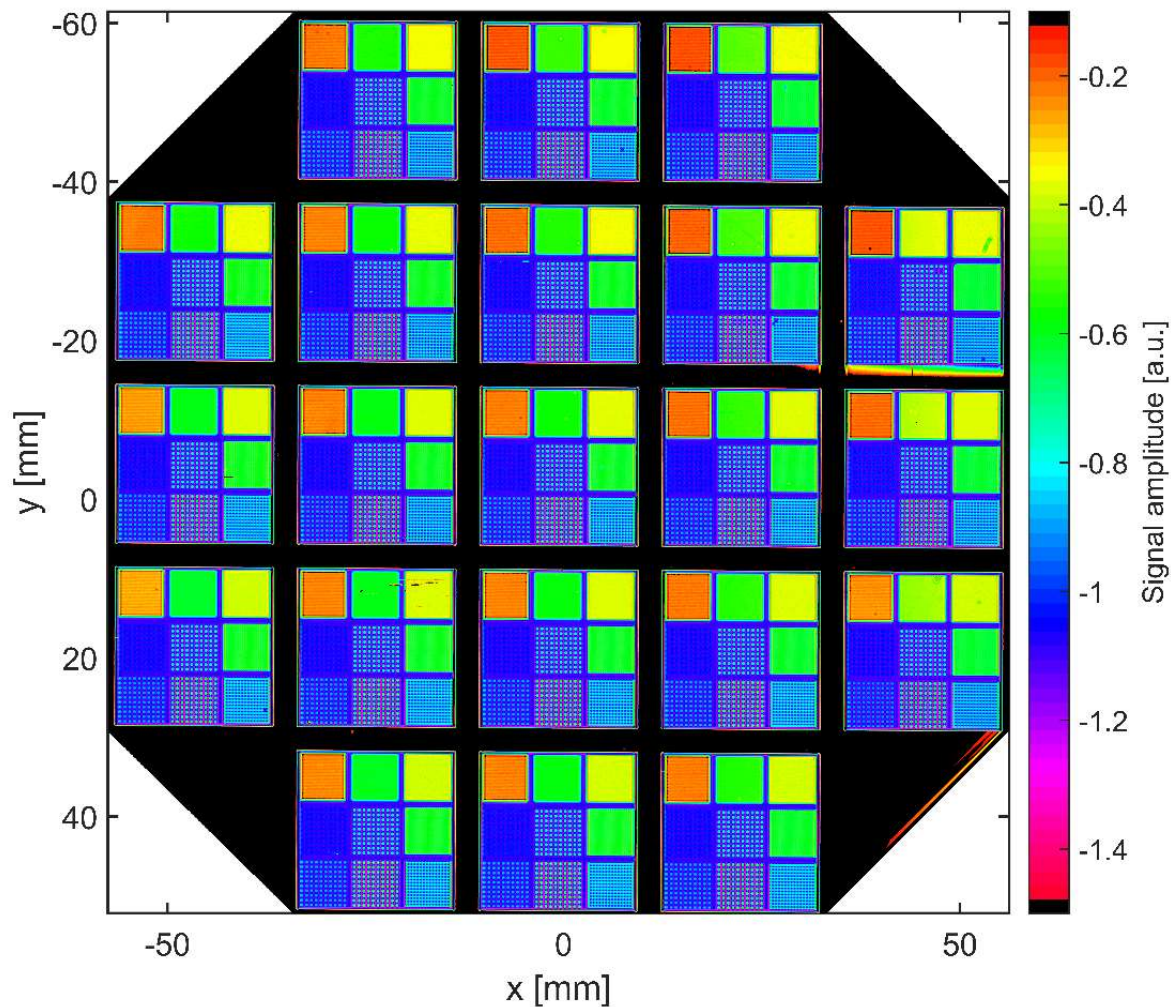
A. Halpin, C. Mennes, A. Bhattacharya, and J. Gómez Rivas

Appl. Phys. Lett. 110, 101105 (2017)

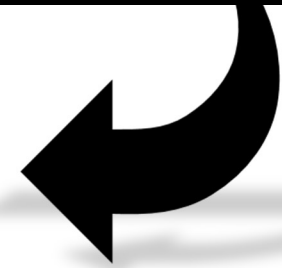


Metamaterial characterization

Measured with TeraSpike microprobe



85000 resonators



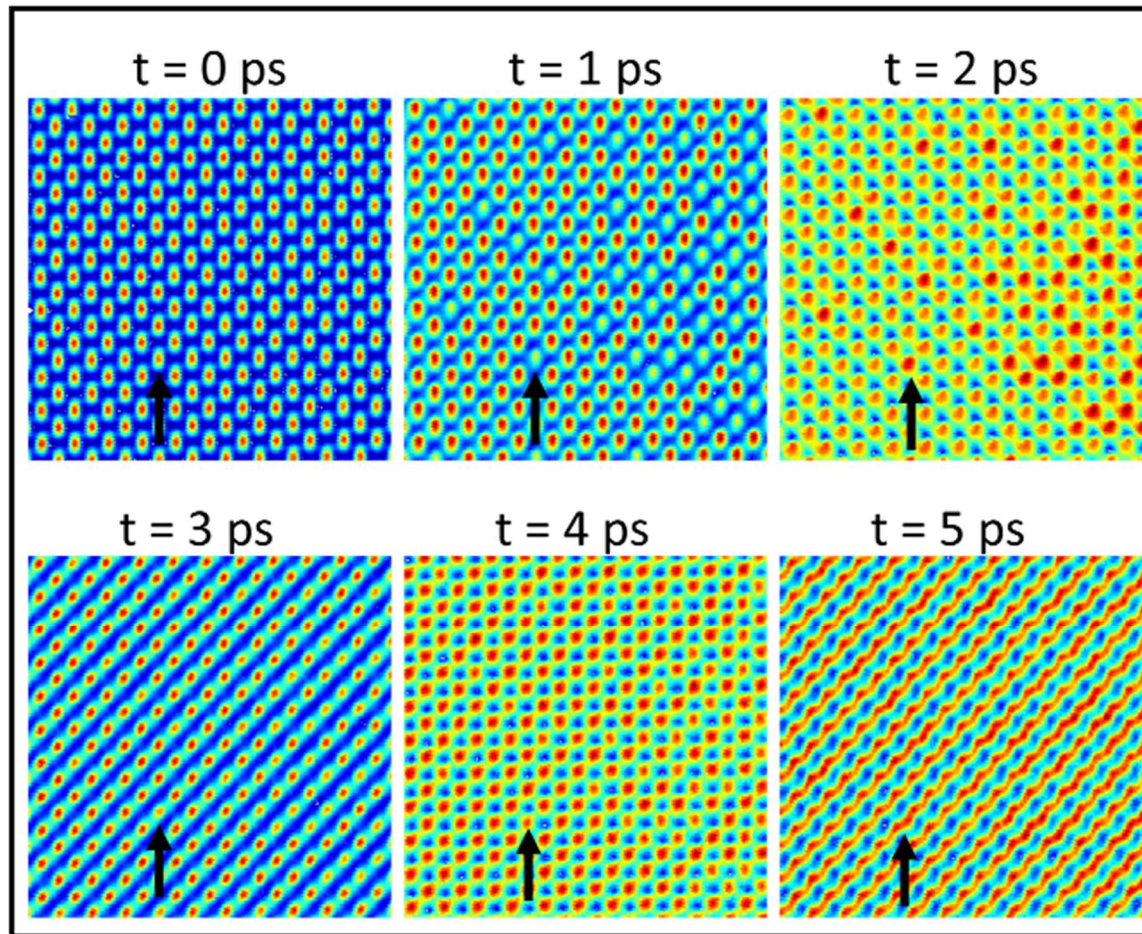


THz structure characterization

Measured with TeraSpike microprobe



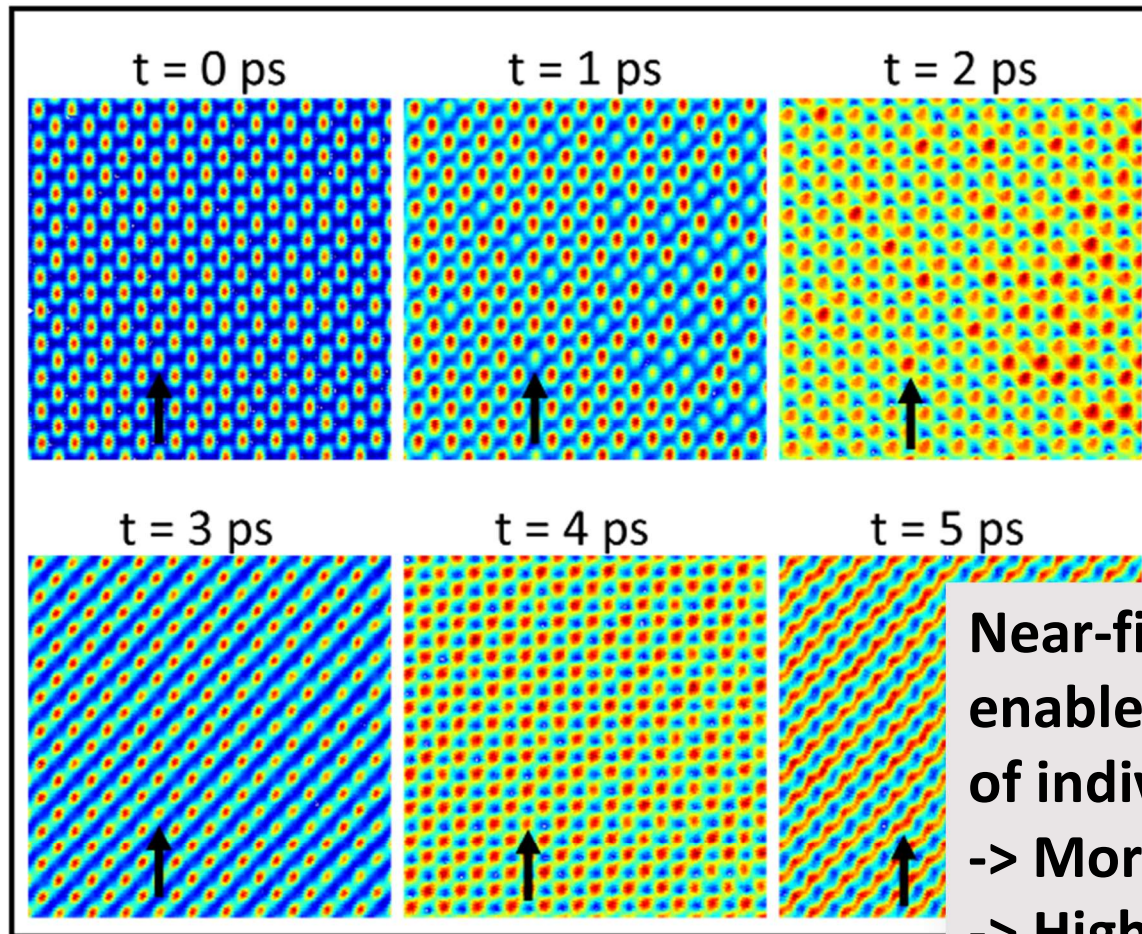
Resonator
covered with
a dielectric layer





THz structure characterization

Measured with TeraSpike microprobe

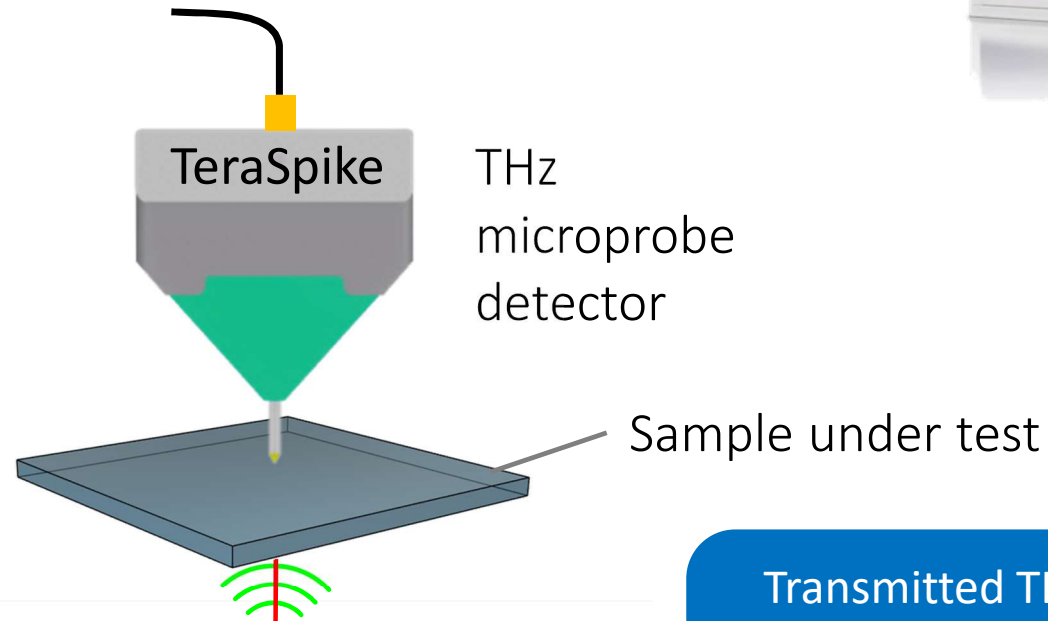


**Near-field detection
enables single read-out
of individual resonators.
-> More information
-> Higher sensitivity**



THz structure characterization

Measured with TeraSpike microprobe



Transmitted THz field



Material Properties:
Sheet resistance

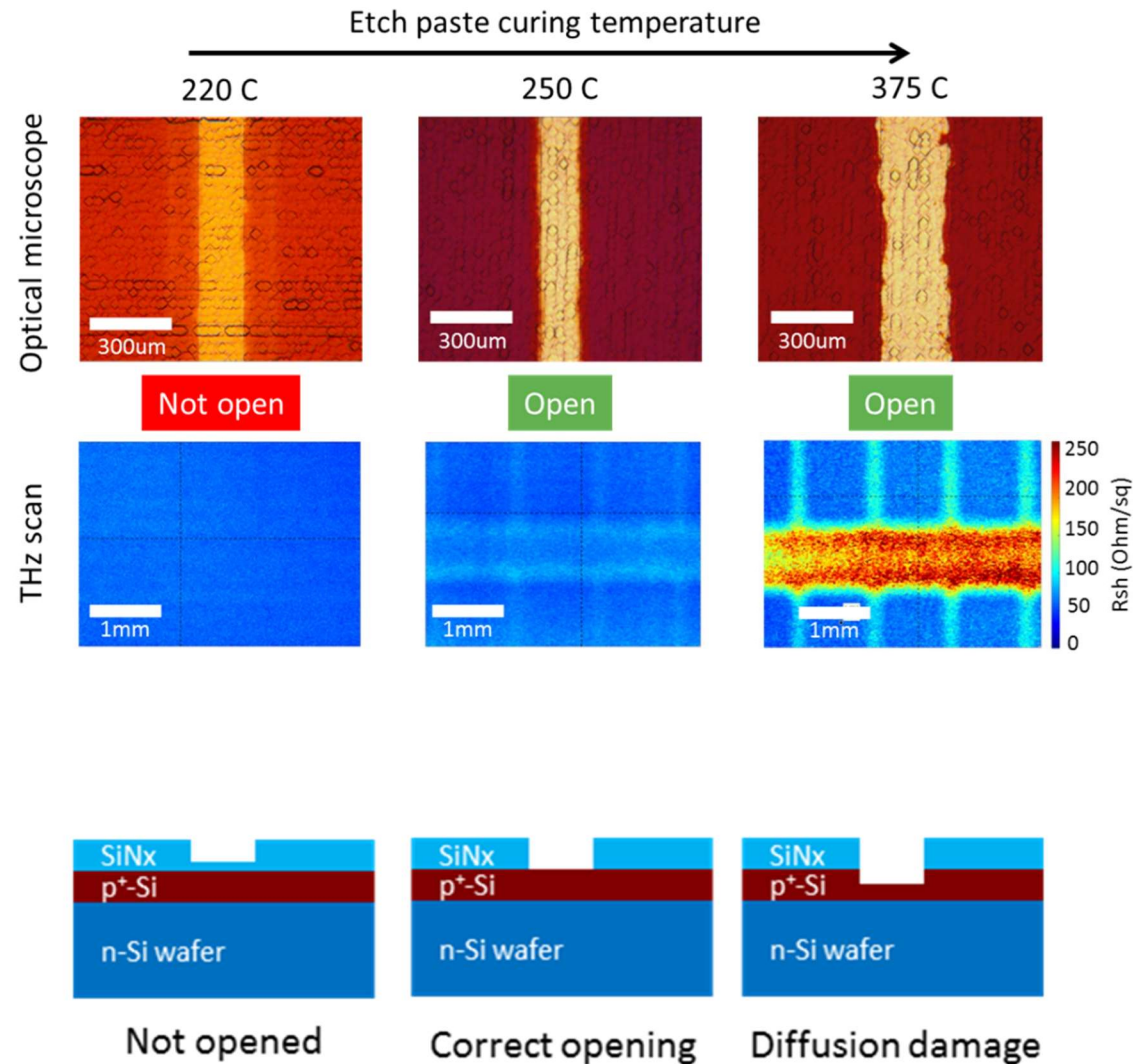
THz emitter
-> xyz-scanned



Dielectric layer opening control on doped Si surfaces

Non-destructive Solar cell process inspection

Measured by:

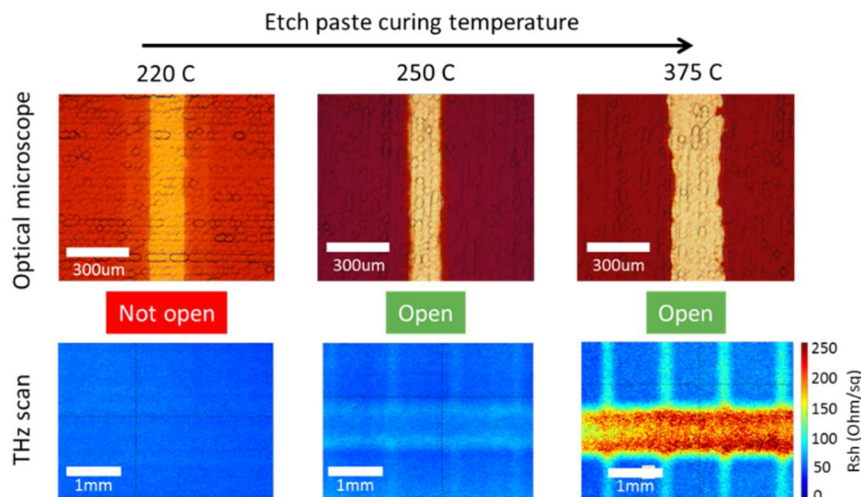




Dielectric layer opening control on doped Si surfaces

Non-destructive Solar cell process inspection

Measured by:



Conclusion:

The THz NF sensor is the first tool offering the required

- spatial resolution
- large area access
- and selectivity to doping layer.

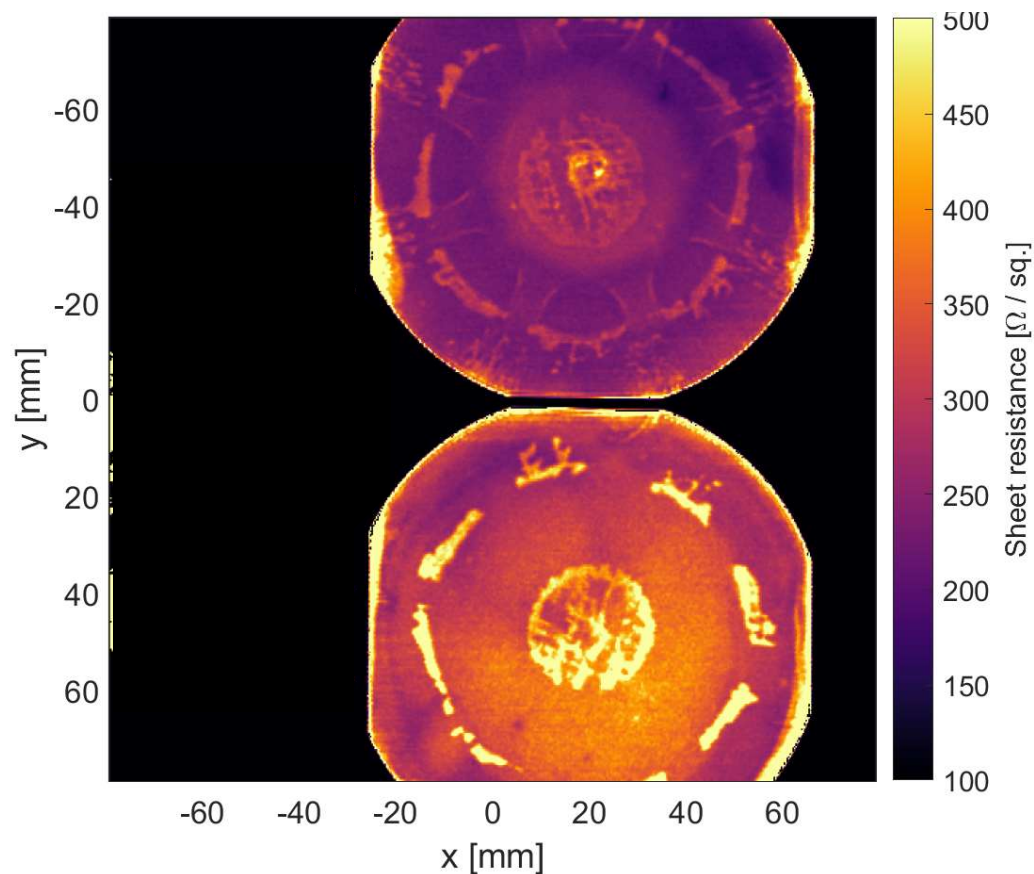
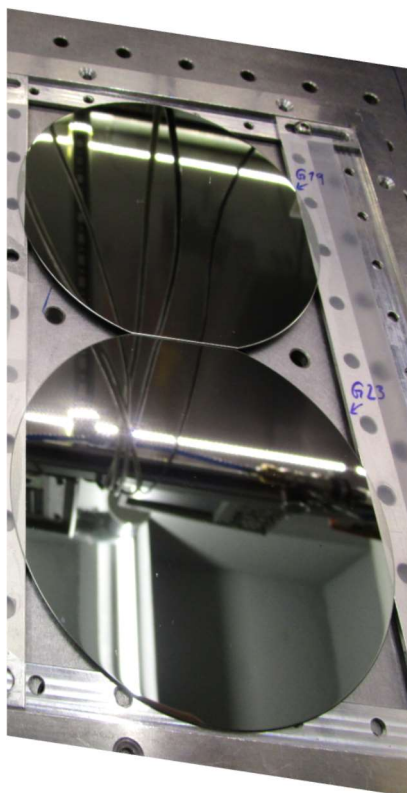
The THz microprobe can also reveal:

- Sheet resistance, Carrier mobility
- Photoconductivity, Carrier lifetime



Graphene on Germanium-Wafers

Sheet resistance imaging



Wafers courtesy of:

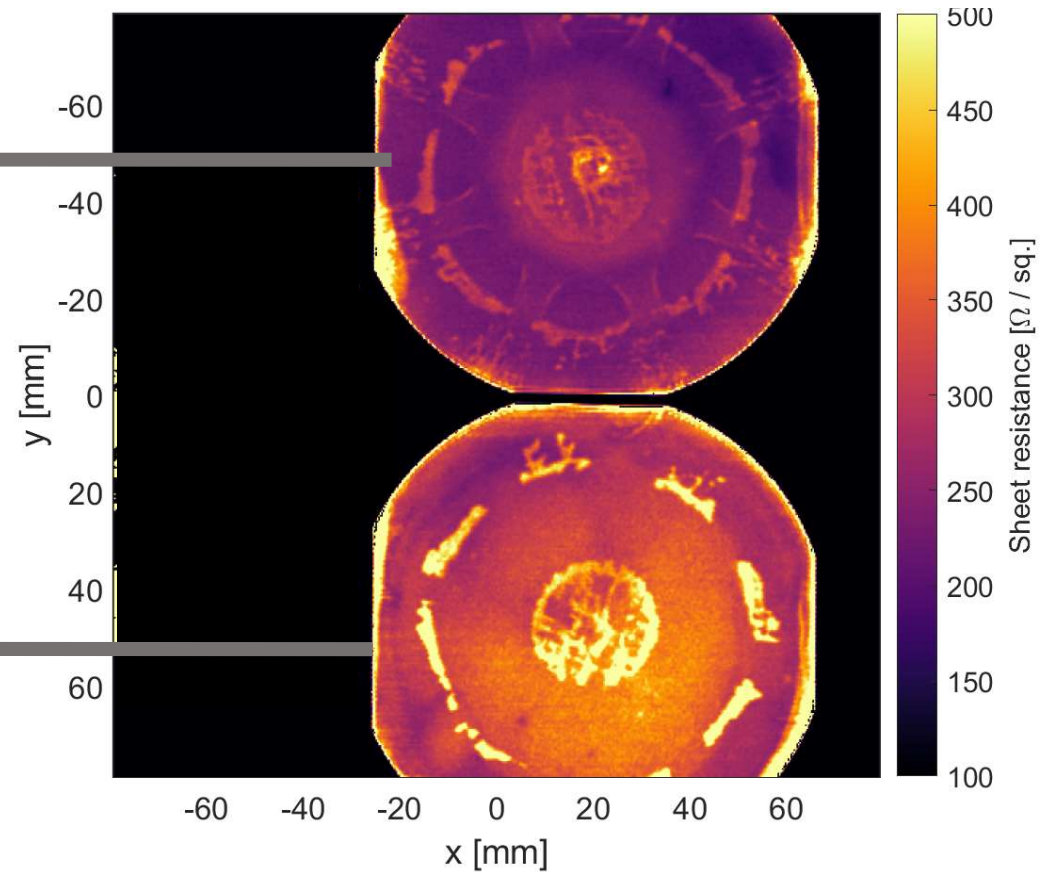
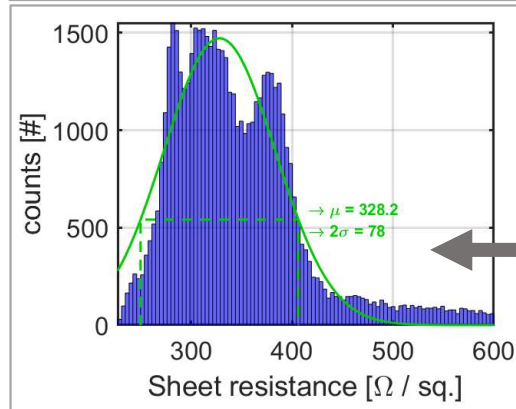
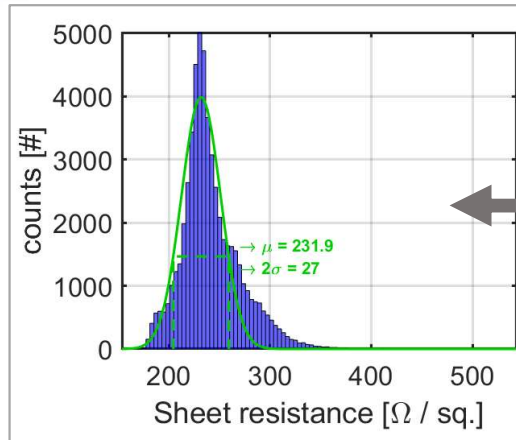
Microelectronics Research Center

THE UNIVERSITY OF TEXAS AT AUSTIN



Graphene on Germanium-Wafers

Sheet resistance imaging



Wafers courtesy of:

Microelectronics Research Center

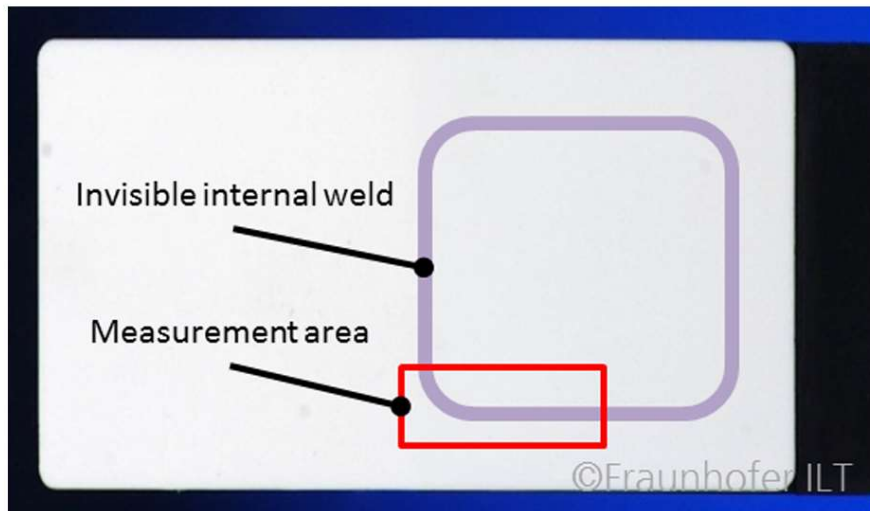
THE UNIVERSITY OF TEXAS AT AUSTIN





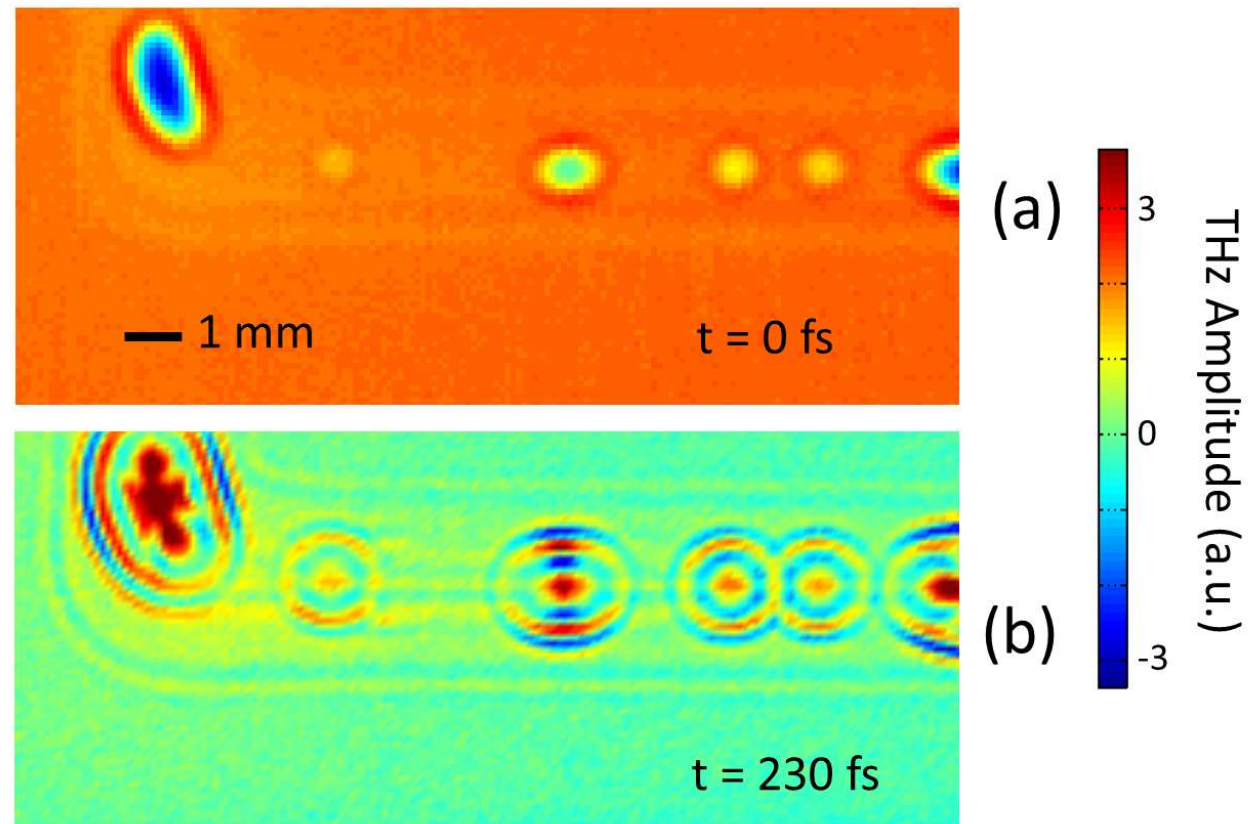
Non-destructive testing

Laser plastic weld inspection



THz microprobing is especially important for plastics which cannot be inspected through light from other spectral ranges.

THz microprobe measurement data

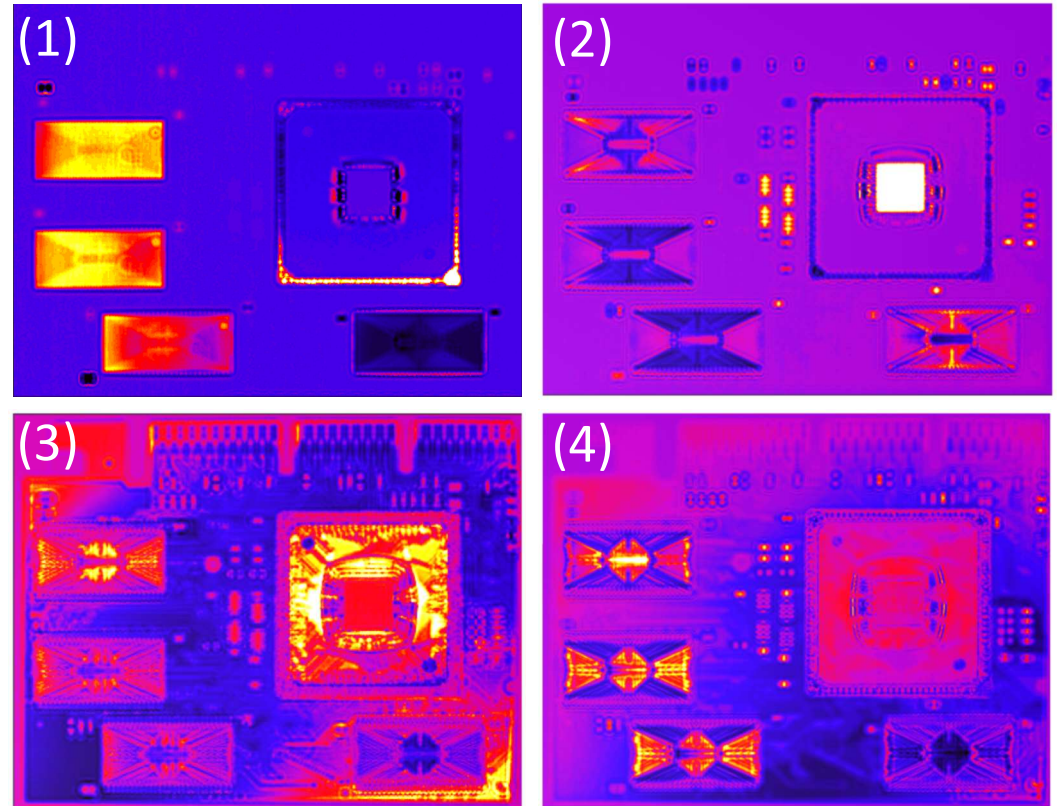
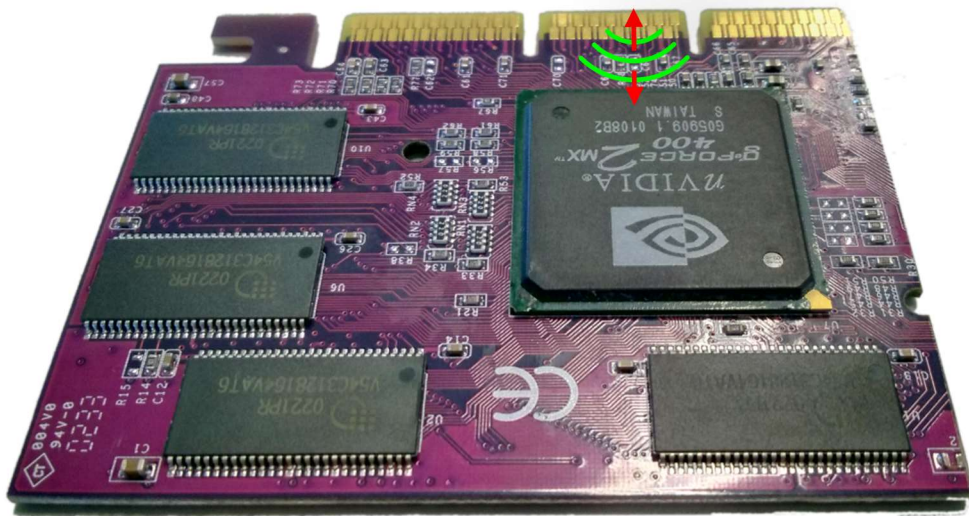
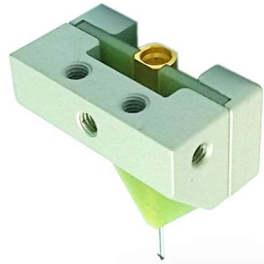




Non-destructive testing

Chip package inspection

Near-field
transceiver
microprobe

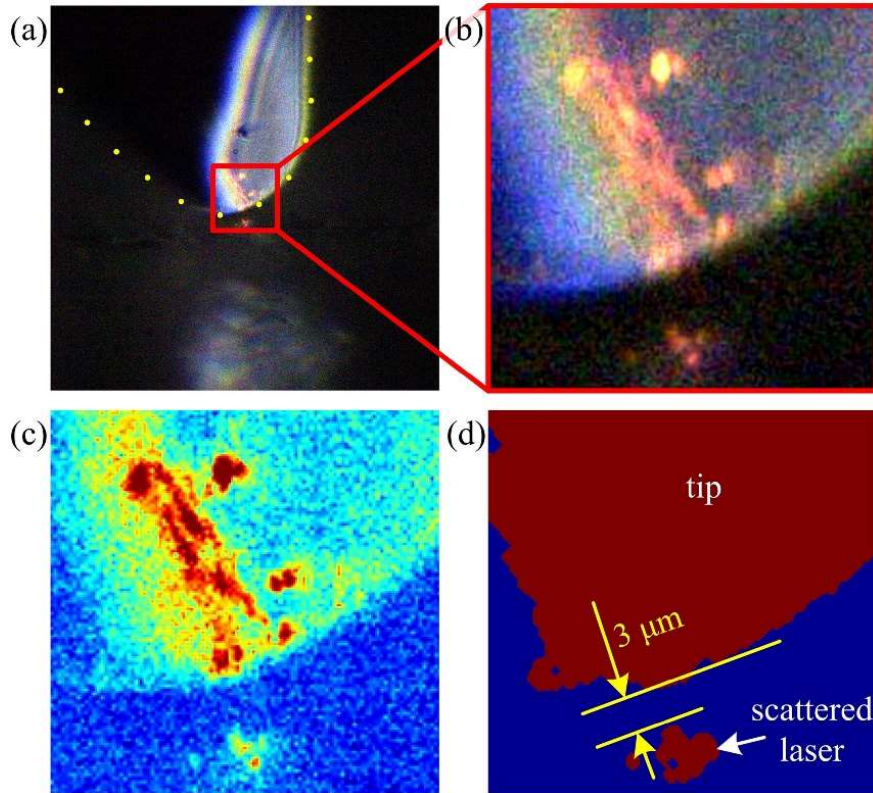


THz images corresponding to different depths



Biological applications

Imaging of brain tissue



**BIOTECHNOLOGY
PROGRESS**

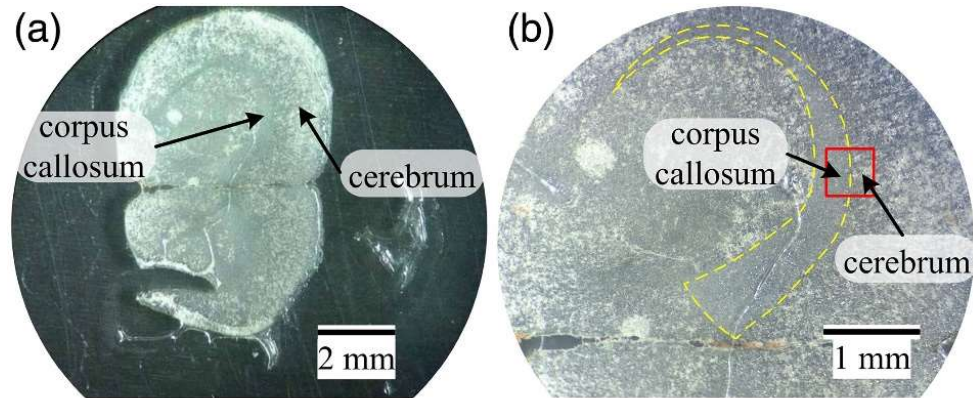
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RESEARCH ARTICLE | [Full Access](#)

Imaging brain tissue slices with terahertz near-field microscopy

Guoshuai Geng, Guangbin Dai, Dandan Li, Shengling Zhou, Zaoxia Li, Zhongbo Yang, Yuehong Xu, Jianguang Han, Tianying Chang, Hong-Liang Cui ✉, Huabin Wang ✉

First published: 10 November 2018 | <https://doi.org/10.1002/btpr.2741> | Citations: 1





Conclusion

Terahertz microprobe technology ...

- ... is going **beyond the capabilities** of standard (free-space) Terahertz inspection.
- ... enables Terahertz-based **non-destructive** **contact-free** inspection
 - at **micron-scale** resolution,
 - on **large wafer-scale areas** and
 - at **high measurement speeds**.
- ... Near-field information is more information!



Terahertz Microprobe-enabled Near-Field Imaging for non- destructive testing applications



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D-52074 Aachen
Germany
www.protemics.com

Thank you for your attention!